



HOSTAFORM® S 9244 XAP®2

POM copolymer, modified Injection molding type, elastomer-containing; with higher impact strength and slightly lower hardness, rigidity and chemical resistance than unmodified acetal copolymer. Reduced emission grade, Emission according to VDA 275 < 5 mg/kg good weld strength. Preliminary Datasheet

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Resin Identification Part Marking Code	POM >POM<		ISO 1043 ISO 11469
Rheological properties			
Melt volume-flow rate Temperature Load	1.4 190 2.16		ISO 1133
Moulding shrinkage, parallel Moulding shrinkage, normal	1.7 1.6		ISO 294-4, 2577 ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus Tensile stress at yield, 50mm/min Tensile strain at yield, 50mm/min Nominal strain at break Flexural modulus Tensile creep modulus, 1h Tensile creep modulus, 1000h Charpy impact strength, 23°C Charpy impact strength, -30°C Charpy notched impact strength, 23°C Charpy rotched impact strength, -30°C Poisson's ratio [P]: Partial Break [C]: Calculated	7 >50 1450 1200 650 N 200 ^[P]	MPa % % MPa	ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 178 ISO 899-1 ISO 899-1 ISO 179/1eU ISO 179/1eU ISO 179/1eA
Thermal properties			
Melting temperature, 10°C/min Temperature of deflection under load, 1.8 MPa Coefficient of linear thermal expansion (CLTE), parallel Electrical properties		°C °C E-6/K	ISO 11357-1/-3 ISO 75-1/-2 ISO 11359-1/-2
Relative permittivity, 100Hz Relative permittivity, 1MHz Dissipation factor, 100Hz Dissipation factor, 1MHz Volume resistivity Surface resistivity Comparative tracking index	60	E-4 E-4 Ohm.m Ohm	IEC 62631-2-1 IEC 62631-2-1 IEC 62631-2-1 IEC 62631-3-1 IEC 62631-3-2 IEC 60112

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Physical/Other properties

Humidity absorption, 2mm	0.2 %	Sim. to ISO 62
Water absorption, 2mm	1.2 %	Sim. to ISO 62
Density	1260 kg/m ³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	195	°C
Min. melt temperature	190	°C
Max. melt temperature	200	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	70	°C
Min. mould temperature	60	°C
Max. mould temperature	80	°C
Hold pressure range	60 - 120	MPa
Back pressure	2	MPa

Characteristics

Processing Injection Moulding

Delivery form Pellets

Additives Release agent

Special characteristics Low emissions, Improved weld line

Additional information

Injection molding Processing

Above pressures, including back pressure, are given as specific or plastic pressures. The back pressure on Hostaform® and Celcon® POM materials should be as low as possible, just enough to remove air from the pellets during feeding.

Processing Notes Pre-Drying

It is normally not necessary to dry HOSTAFORM. However, should there be surface moisture (condensate) on the molding compound as a result of incorrect storage, drying is required. A circulating air drying cabinet can be used for this purpose

Storage

The product can then be stored in standard conditions until processed.

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Automotive

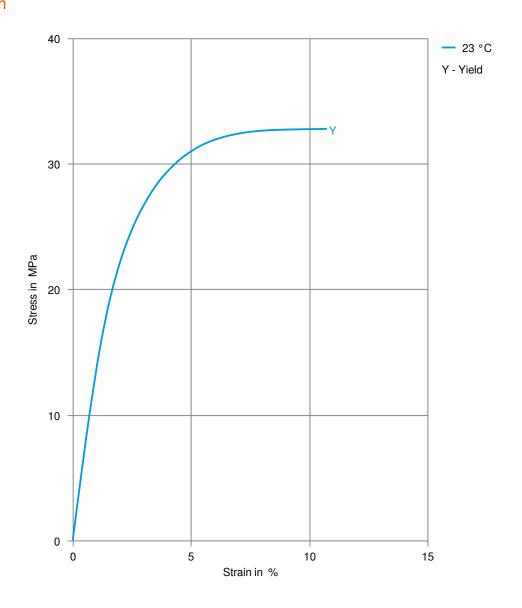
OEM STANDARD ADDITIONAL INFORMATION

Mercedes-Benz DBL5404 BQF

Renault UB15, No Spec, Special Part Approval, See

Your CE Account Manager.

Stress-strain



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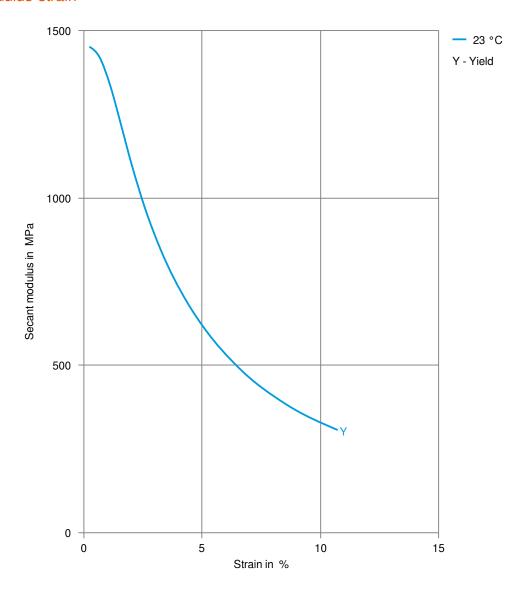
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HOSTAFORM® S 9244 XAP®2 HOSTAFORM®

Secant modulus-strain



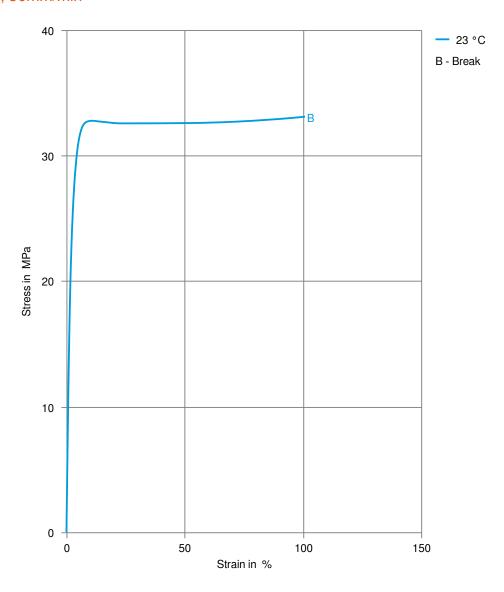
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Stress-strain, 50mm/min



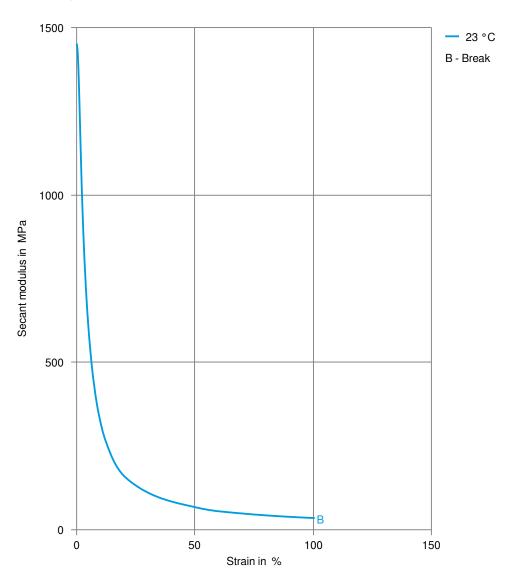
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Secant modulus-strain, 50mm/min



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